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REMARKS

Claim 1 has been amended to specify that the method of manufacturing an integrated circuit carrier includes creating a serpentine member between neighbouring island-defining portions by removing material from the substrate, thereby reducing thermal strains involving the said island-defining portions. Support for this amendment is found, for example, at page 4, line 32 to page 5, line 5; where it is clearly stated that a rigidity reducing arrangement is in the form of a serpentine member 22. Further support may also be found by referring to figures 3 to 6, which illustrate examples of serpentine member 22.

In item 2, at page 2 of the Office Action, the Examiner rejects claims 1, 6, and 8-9 under 35 USC 102(b), as being anticipated by Root (US 4,802,277). A claim is anticipated if all of its limitations are present in a single reference in the prior art. Because all of the limitations of the claims of the present invention, as amended, are not present in Root, as discussed below, the present invention is not anticipated by Root. Reconsideration and withdrawal of the rejection is respectfully requested.

The Examiner asserts that Root discloses secondary rigidity reducing arrangements 15, that are presented in Root as elongated slots. Further, Root discloses demarcating at least one receiving zone by etching a recess 15 in the substrate 20. Root also discloses a support bridge 13 that interconnects the chip carrier regions 23. Referring to column 4, line 26 of Root, the chip carriers 11 are separated from the array 10 by breaking the support bridges 13. Hence, the support bridges 13 function to temporarily hold the chip carriers 11 in place. It is submitted that they do not function as a rigidity-reducing arrangement.

Claim 1 has been currently amended to require a serpentine member between neighbouring island-defining portions that reduces thermal strains involved the island-defining portions. Such a serpentine member is not disclosed or suggested in Root. The elongated slots 15, or the support bridges 13, are not, and could not function as, serpentine members acting to reduce thermal strains.

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In item 4 at page 2 of the Office Action, the Examiner rejects claim 7 under 34 USC 103(a) as being unpatentable over Root in view of Akram *et al* (US 6,365,967). Reconsideration and withdrawal of this objection is respectfully requested.

At item 5 of page 3 of the Office Action, the Examiner rejects claims 2-3 under 35 USC 103(a) as being unpatentable over Root in view of Hargis (US 4,426,773). Reconsideration and withdrawal of this objection is also respectfully requested.

Obviousness can only be established by combining or modifying teachings of the prior art to produce the claimed invention where there is some teaching, suggestion or motivation to do so found either in the references themselves or in the knowledge generally available to one skilled in the art.

Having regard to claim 1 as currently amended, claim 7 is not obvious with regard to Root in view of Akram. Furthermore, claims 2-3 are not obvious with regard to Root in view of Hargis. Neither the combination of Root and Akram, or Root and Hargis, disclose or suggest the feature of creating a serpentine member between neighbouring island-defining portions by removing material from the substrate, thereby reducing thermal strains involving the said island-defining portions. As currently amended, claim 1 is submitted to be patentable over Root in view of Akram, and Root in view of Hargis, it is likewise respectfully submitted that claims 2, 3 and 7, which depend from currently amended claim 1, are patentable over these combinations of prior art documents.

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CONCLUSION

In view of the foregoing, it is respectfully requested that the Examiner reconsider and withdraw the objections under 35 USC §102(b) and 35 USC §103(a). The present application is believed to be in condition for allowance. Accordingly, the Applicant respectfully requests a Notice of Allowance for all the claims presently under examination.

Very respectfully,

Applicant:



KIA SILVERBROOK

C/o: Silverbrook Research Pty Ltd
393 Darling Street
Balmain NSW 2041, Australia

Email: Kia.Silverbrook@silverbrookresearch.com

Telephone: +612 9818 6633

Facsimile: +61 2 9818 6711